



Promex Quik-Pak Exhibits Air Cavity Plastic and Overmolded QFNs in Booth 809 at IEEE MTT International Microwave Symposium (IMS) June 10-15

Santa Clara, CA – June 8, 2018 – [Quik-Pak](#), a division of Promex providing innovative microelectronic packaging and assembly solutions for complex devices, will exhibit Air Cavity Plastic and Overmolded QFN Packages for RF/microwave, MEMS and sensor applications in Booth 809 at the [IEEE MTT International Microwave Symposium \(IMS\)](#), June 10-15, 2018 in Philadelphia, PA.

The Quik-Pak [air cavity plastic QFN packages](#), also known as Open-molded Plastic Packages or OmPPs, feature gold plating for wire bondability, RoHS/REACH-compliant green molding compound, highly conductive short interconnects and JEDEC outlines. The OmPP air-cavity QFN package, which consists of a copper leadframe, plastic molded body (open and not sealed), and either a ceramic or a plastic lid, is usable to about 20 GHz. Custom designs have been developed for optical, photonic, MEMS, K band, Ka band and other applications. Matching ceramic, plastic, quartz or glass lids with b-stage epoxy seals are available. More than 30 off-the-shelf sizes are in stock for prototype, mid-volume and production-volume requirements. Custom design cycle time can be less than one month.

The Quik-Pak [overmolded, open-tooled QFN packages](#) for quick-turn engineering builds, high mix/low volume assembly and onshore volume production are available for purchase off the shelf in over 35 designs, from 2x2 mm to 12x12 mm, with multiple thicknesses. Five-day delivery of assembled QFNs is standard. All QFNs are RoHS compliant and utilize NiPdAu-plated lead frames. Custom designs are also available with quick lead times.

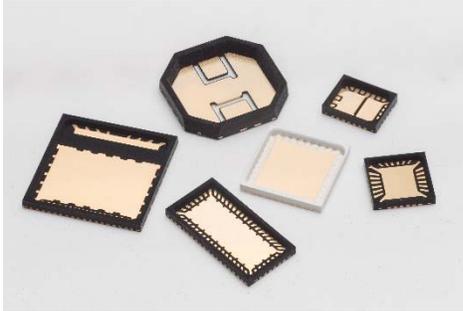
The [IEEE MTT International Microwave Symposium \(IMS\)](#) is the premier annual international meeting for technologists involved in all aspects of microwave theory and practice. More than 600 companies will exhibit the latest developments in packaging, materials, devices, components and subsystems, as well as design and simulation software and test/measurement equipment.

ABOUT PROMEX QUIK-PAK

The Promex Quik-Pak Division provides IC packaging, assembly and wafer preparation services for prototype to full-production needs from its ISO 9001:2008 certified, ITAR registered facility in San Diego, California. At IMS Booth 809 ask for East Coast and Europe Technical Sales Manager Bill Lawrence or call him at (802) 309-0327. For information about Quik-Pak products, visit <http://www.icproto.com> or call 858-674-4676.

Promex provides design for manufacturing services coupled with materials science expertise and broad assembly capabilities for small- to mid-volume onshore production. Services include RoHS-optimized SMT, wafer thinning, dicing, wirebond, flip chip, overmolding and Class 100/Class 1000 cleanrooms. IC

packaging, Located in Silicon Valley since 1975, Promex is ISO 13485:2016 and ISO 9001:2015 certified, IPC certified and ITAR registered. For more information contact Promex Director of Sales and Marketing Rosie Medina, or visit <http://www.promex-ind.com>, or call Promex at 408-496-0222.



[Air cavity plastic QFN packages](#) for RF/microwave, MEMS and sensor applications and [overmolded QFN packages](#) for quick-turn engineering builds, high mix/low volume assembly and onshore volume production are available from Promex Quik-Pak in over 35 off-the-shelf designs.